

DERWENT-ACC-NO: 2002-251211  
DERWENT-WEEK: 200230  
COPYRIGHT 1999 DERWENT INFORMATION LTD

TITLE: Semiconductor package including double underfill area

INVENTOR: CHUN, J H; NOH, Y H ; YOON, H G

PATENT-ASSIGNEE: SAMSUNG ELECTRONICS CO LTD[SMSU]

PRIORITY-DATA: 1999KR-0055694 (December 8, 1999)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE
PAGES	MAIN-IPC	
(KR 2001054743)	July 2, 2001	N/A
001	H01L 021/60	
A		

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO
APPL-DATE		
KR2001054743A	N/A	1999KR-0055694
December 8, 1999		

INT-CL\_(IPC): H01L021/60

ABSTRACTED-PUB-NO: KR2001054743A

BASIC-ABSTRACT: NOVELTY - A semiconductor package including double underfill area is provided to prevent a fillet part of underfill area from cracking.

DETAILED DESCRIPTION - A bonding pad(112) is formed on a semiconductor chip(110). The bonding pad(112) is connected with the semiconductor chip(110) through a bump(120). The semiconductor chip(110) is composed of a substrate(130), an external connection terminal(140) such as solder balls, and a double underfill area(150). The double underfill area(150) consists of the first underfill area(154) and the second underfill



area(156). The first  
underfill area(154) locates between the semiconductor  
chip(110) and the  
substrate(130), and is filled with liquid type of a sort of  
epoxy material.

The second underfill area(156) positions around the  
semiconductor chips(110),  
and it is reclaimed with a sort of silicon material.

CHOSEN-DRAWING: Dwg.1/10

TITLE-TERMS:  
SEMICONDUCTOR PACKAGE DOUBLE AREA

DERWENT-CLASS: U11

EPI-CODES: U11-D01C9;





